## SFH 4770SR7S

#### SYNIOS® P2720

850 nm; 60°







### **Applications**

- CCTV Surveillance

- Safety systems and CCTV

Eye Tracking

#### Features:

- Corrosion Robustness Class: 3B

- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

- IR lightsource with high efficiency

Double stack emitter

Low thermal resistance (Max. 9 K/W)

- Centroid wavelength 850 nm

## **Ordering Information**

Type Total radiant flux 1) Total radiant flux 1) Ordering Code

typ.

 $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$   $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ 

SFH 4770SR7S 800 ... 1600 mW 1,360 mW TBD





## **Maximum Ratings**

T<sub>A</sub> = 25 °C

| Parameter                                     | Symbol           | Values |         |
|---|------------------|--------|---------|
| Operating temperature                         | T <sub>op</sub>  | min.   | -40 °C  |
|   | ·                | max.   | 100 °C  |
| Storage temperature                           | $T_{stg}$        | min.   | -40 °C  |
|   | 2.9              | max.   | 100 °C  |
| Junction temperature                          | T <sub>j</sub>   | max.   | 145 °C  |
| Reverse voltage 2)                            | $V_R$            | max.   | 12 V    |
| Forward current                               | I <sub>F</sub>   | max.   | 1500 mA |
| Surge current                                 | I <sub>FSM</sub> | max.   | 3 A     |
| $t_{p} \le 200  \mu\text{s}; D = 0$           |                  |        |         |
| Power consumption                             | P <sub>tot</sub> | max.   | 5800 mW |
| ESD withstand voltage                         | $V_{ESD}$        | max.   | 2 kV    |
| acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2) |                  |        |         |

For the forward current and power consumption please see "maximum permissible forward current" diagram





### **Characteristics**

 $I_{_{\rm F}}$  = 1000 mA;  $t_{_{
m D}}$  = 10 ms;  $T_{_{
m A}}$  = 25 °C

| rameter Symbol  |                            | Values       |                  |
|---|----------------------------|--------------|------------------|
| Peak wavelength   | $\lambda_{peak}$           | typ.         | 860 nm           |
| Centroid wavelength   | $\lambda_{	ext{centroid}}$ | typ.         | 850 nm           |
| Spectral bandwidth at 50% I <sub>rel,max</sub>                    | Δλ                         | typ.         | 30 nm            |
| Half angle  | φ                          | typ.         | 30 °             |
| Dimensions of active chip area                                    | LxW                        | typ.         | 1 x 1<br>mm x mm |
| Rise time (10% / 90%) $I_F = 3 \text{ A}; R_L = 50 \Omega$        | t,                         | typ.         | 12 ns            |
| Fall time (10% / 90%) $I_F = 3 \text{ A}; R_L = 50 \Omega$        | t <sub>f</sub>             | typ.         | 15 ns            |
| Forward voltage   | $V_{F}$                    | typ.<br>max. | 3.15 V<br>3.5 V  |
| Forward voltage $I_F = 1.5 \text{ A}; t_p = 100 \mu\text{s}$      | $V_{F}$                    | typ.<br>max. | 3.3 V<br>3.85 V  |
| Forward voltage $I_F = 3 \text{ A}; t_p = 100  \mu\text{s}$       | $V_{F}$                    | typ.<br>max. | 3.8 V<br>4.7 V   |
| Reverse current <sup>2)</sup> V <sub>R</sub> = 5 V                | I <sub>R</sub>             | max.<br>typ. | 10 μA<br>0.01 μA |
| Radiant intensity   | l <sub>e</sub>             | typ.         | 1050 mW/sr       |
| Radiant intensity $I_F = 1.5 \text{ A}$ ; $t_p = 100 \mu\text{s}$ | l <sub>e</sub>             | typ.         | 1550 mW/sr       |
| Temperature coefficient of brightness                             | TC <sub>I</sub>            | typ.         | -0.3 % / K       |
| Temperature coefficient of voltage                                | $TC_v$                     | typ.         | -2 mV / K        |
| Temperature coefficient of wavelength                             | $TC_{\lambda}$             | typ.         | 0.3 nm / K       |
| Thermal resistance junction solder point real 3)                  | $R_{\mathrm{thJS}}$        | max.         | 9.0 K / W        |





# **Brightness Groups**

T<sub>A</sub> = 25 °C

Group Total radiant flux 1) Total radiant flux 1)

> $I_F = 1000 \text{ mA}; t_D = 10 \text{ ms}$  $I_F = 1000 \text{ mA}; t_D = 10 \text{ ms}$

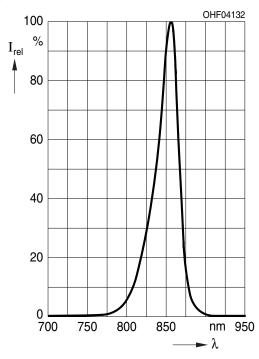
min. max. Фе

800 mW 1600 mW SFH4770SR7S

### Relative Spectral Emission 4), 5)

 $\boldsymbol{\varphi}_{e}$ 

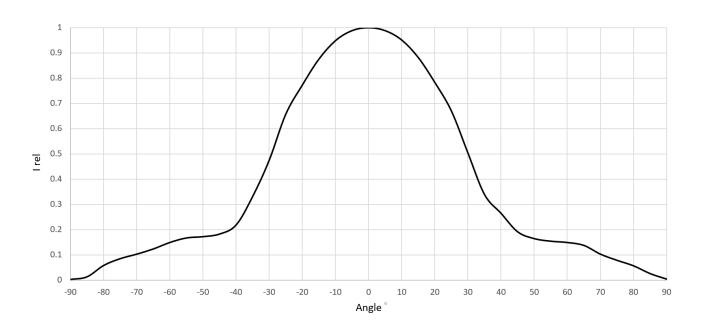
 $I_{rel} = f(\lambda); I_F = 1000 \text{ mA}; t_p = 10 \text{ ms}$ 





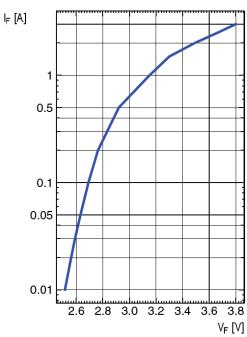
### Radiation Characteristics 4), 5)

$$I_{rel} = f(\phi)$$



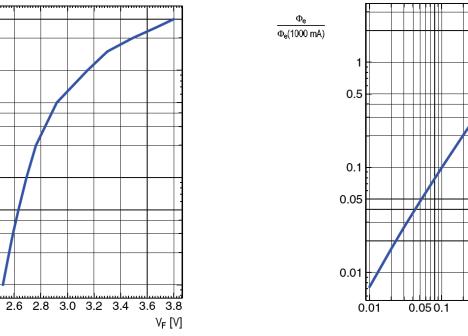
#### Forward current 4), 5)

 $I_F = f(V_F)$ ; single pulse;  $t_p = 100 \mu s$ 



#### Relative Total Radiant Flux 4), 5)

 $\Phi_e/\Phi_e$ (1000mA) = f (I<sub>F</sub>); single pulse; t<sub>D</sub> = 100  $\mu$ s



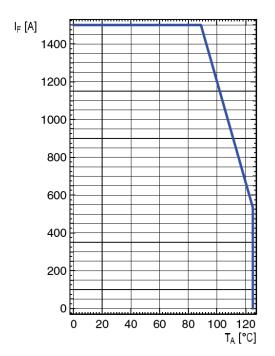


I<sub>F</sub> [A]

0.5 1

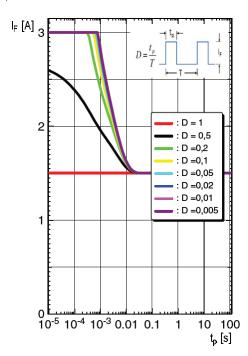
#### Max. Permissible Forward Current

$$I_{F,max} = f(T_S); R_{thJS} = 9.0 K/W$$



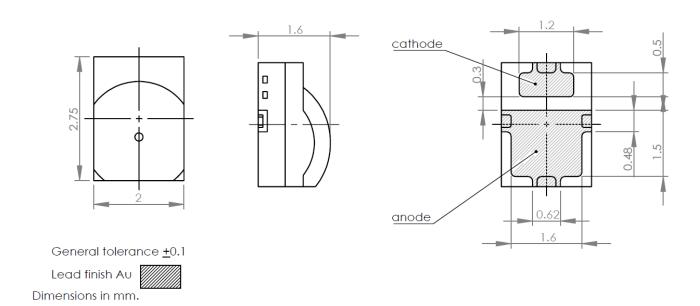
### **Permissible Pulse Handling Capability**

 $I_F = f(t_p)$ ; duty cycle D = parameter;  $T_S = 85$ °C





## **Dimensional Drawing** 6)



**Approximate Weight:** 12.0 mg

Package marking: Cathode

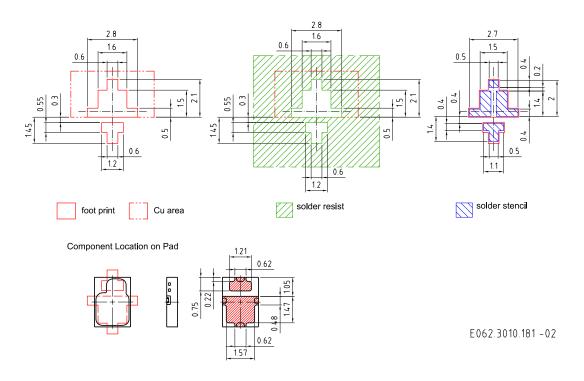
Corrosion test: Class: 3B

Test condition:  $40^{\circ}$ C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter then IEC

60068-2-43)

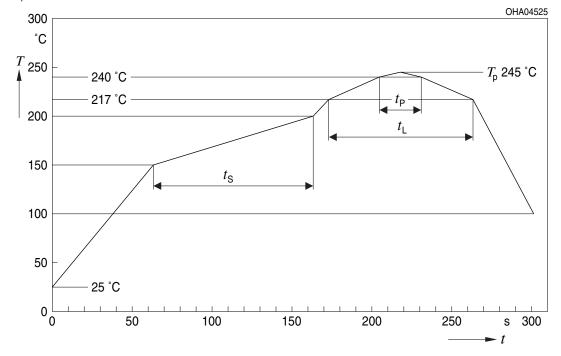


#### Recommended Solder Pad 6)



### **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



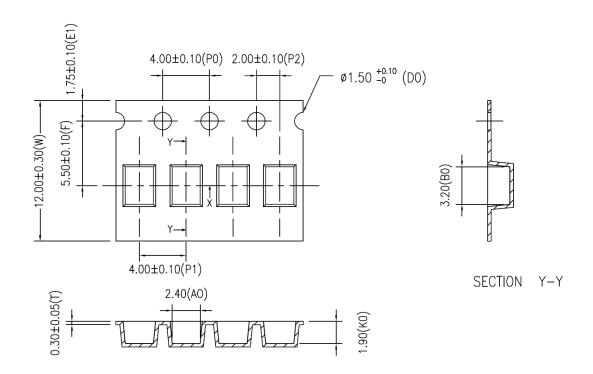


#### SFH 4770SR7S

| Profile Feature   | Symbol                     | Pb      | Pb-Free (SnAgCu) Assembly |         | Unit |
|---|----------------------------|---------|---------------------------|---------|------|
|   | - ,                        | Minimum | Recommendation            | Maximum |      |
| Ramp-up rate to preheat*) 25 °C to 150 °C                               |                            |         | 2                         | 3       | K/s  |
| Time t <sub>s</sub> T <sub>Smin</sub> to T <sub>Smax</sub>              | t <sub>s</sub>             | 60      | 100                       | 120     | S    |
| Ramp-up rate to peak $^{*)}$ T <sub>Smax</sub> to T <sub>P</sub>        |                            |         | 2                         | 3       | K/s  |
| Liquidus temperature  | $T_{L}$                    |         | 217                       |         | °C   |
| Time above liquidus temperature   | $t_{\scriptscriptstyle L}$ |         | 80                        | 100     | S    |
| Peak temperature  | T <sub>P</sub>             |         | 245                       | 260     | °C   |
| Time within 5 °C of the specified peak temperature T <sub>p</sub> - 5 K | t <sub>P</sub>             | 10      | 20                        | 30      | S    |
| Ramp-down rate* T <sub>P</sub> to 100 °C                                |                            |         | 3                         | 6       | K/s  |
| Time<br>25 °C to T <sub>P</sub>   |                            |         |                           | 480     | S    |

All temperatures refer to the center of the package, measured on the top of the component

# Taping 6)



SECTION X-X

Dimensions in mm.

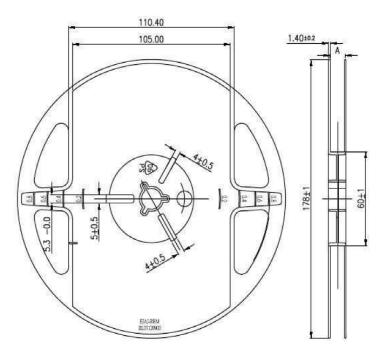


<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

## Tape and Reel 7)

### Reel

12 mm tape with 2000 pcs. on  $\varnothing$  180 mm reel





#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



#### **Disclaimer**

#### Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

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#### Glossary

- 1) **Total radiant flux**: Measured with integrating sphere.
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Testing temperature:  $T_A = 25$ °C
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- <sup>7)</sup> **Tape and Reel**: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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